

DECLARATION AND POWER OF ATTORNEY

As a below-named inventor, I hereby declare that:

My residence, post office address, and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

GAIT DETECTION SYSTEM, GAIT DETECTION APPARATUS,  
DEVICE, AND GAIT DETECTION METHOD

the specification of which  
(check one)

X  is attached hereto.

\_\_\_\_\_ was filed on \_\_\_\_\_ as \_\_\_\_\_

Application Serial No. \_\_\_\_\_

and was amended on \_\_\_\_\_  
(if applicable)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information of which I am aware which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)			Priority Claimed	
<u>Number</u>	<u>Country</u>	<u>Filing Date</u>	<u>Yes</u>	<u>No</u>
<u>P2000-396830</u>	<u>Japan</u>	<u>December 27, 2000</u>	<u> X </u>	_____

Declaration and Power of Attorney

Page 2

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States Application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

<u>Application Serial No.</u>	<u>Filing Date</u>	<u>Status</u>
_____	_____	_____
_____	_____	_____

And I hereby appoint Jay H. Maioli, Reg. No. 27,213; Donald S. Dowden, Reg. No. 20,701; William E. Pelton, Reg. No. 25,702; Peter J. Phillips, Reg. No. 29,691; Gerald W. Griffin, Reg. No. 18,886; Ivan S. Kavrukov, Reg. No. 25,161; Christopher C. Dunham, Reg. No. 22,031; Norman H. Zivin, Reg. No. 25,385; John P. White, Reg. No. 28,678; and Robert D. Katz, Reg. No. 30,141; and each and all of them, all c/o Cooper & Dunham, 1185 Avenue of the Americas, New York, NY 10036 (Tel. (212) 278-0400), my attorneys, each with full power of substitution and revocation, to receive the patent, to transact all business in the Patent and Trademark Office connected therewith and to file any International Applications which are based thereon under the provisions of the Patent Cooperation Treaty.

Please address all communications, and direct all telephone calls, regarding this application to

**JAY H. MAIOLI**  
Cooper & Dunham LLP  
1185 Avenue of the Americas  
New York, New York 10036  
Tel. (212) 278-0400

Reg. No. 27,213

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or  
First joint inventor Kiyoaki Takiguchi

Inventor's signature \_\_\_\_\_

Citizenship Japanese Date of Signature \_\_\_\_\_

Residence Kanagawa, Japan

Post Office Address c/o Sony Corporation , 7-35 Kitashinagawa, 6-chome,

Shinagawa-ku, Tokyo, Japan

Case	Material	Temperature (°C)	Strain Rate (s <sup>-1</sup> )	Yield Stress (MPa)	Ultimate Tensile Stress (MPa)	Elongation to Break (%)
1	Aluminum	25	0.001	100	150	10
2	Aluminum	25	0.01	110	160	12
3	Aluminum	25	0.1	120	170	15
4	Aluminum	25	1	130	180	18
5	Aluminum	25	10	140	190	20
6	Aluminum	25	100	150	200	22
7	Aluminum	25	1000	160	210	25
8	Aluminum	25	10000	170	220	28
9	Aluminum	25	100000	180	230	30
10	Aluminum	25	1000000	190	240	32
11	Aluminum	25	10000000	200	250	35
12	Aluminum	25	100000000	210	260	38
13	Aluminum	25	1000000000	220	270	40
14	Aluminum	25	10000000000	230	280	42
15	Aluminum	25	100000000000	240	290	45
16	Aluminum	25	1000000000000	250	300	48
17	Aluminum	25	10000000000000	260	310	50
18	Aluminum	25	100000000000000	270	320	52
19	Aluminum	25	1000000000000000	280	330	55
20	Aluminum	25	10000000000000000	290	340	58
21	Aluminum	25	100000000000000000	300	350	60
22	Aluminum	25	1000000000000000000	310	360	62
23	Aluminum	25	10000000000000000000	320	370	65
24	Aluminum	25	100000000000000000000	330	380	68
25	Aluminum	25	1000000000000000000000	340	390	70
26	Aluminum	25	10000000000000000000000	350	400	72
27	Aluminum	25	100000000000000000000000	360	410	75
28	Aluminum	25	1000000000000000000000000	370	420	78
29	Aluminum	25	10000000000000000000000000	380	430	80
30	Aluminum	25	100000000000000000000000000	390	440	82
31	Aluminum	25	1000000000000000000000000000	400	450	85
32	Aluminum	25	10000000000000000000000000000	410	460	88
33	Aluminum	25	100000000000000000000000000000	420	470	90
34	Aluminum	25	1000000000000000000000000000000	430	480	92
35	Aluminum	25	10000000000000000000000000000000	440	490	95
36	Aluminum	25	100000000000000000000000000000000	450	500	98
37	Aluminum	25	1000000000000000000000000000000000	460	510	100
38	Aluminum	25	10000000000000000000000000000000000	470	520	102
39	Aluminum	25	100000000000000000000000000000000000	480	530	105
40	Aluminum	25	1000000000000000000000000000000000000	490	540	108
41	Aluminum	25	10000000000000000000000000000000000000	500	550	110
42	Aluminum	25	100000000000000000000000000000000000000	510	560	112
43	Aluminum	25	1000000000000000000000000000000000000000	520	570	115
44	Aluminum	25	100	530	580	118
45	Aluminum	25	1000	540	590	120
46	Aluminum	25	100	550	600	122
47	Aluminum	25	1000	560	610	125
48	Aluminum	25				

**Inventor's signature** \_\_\_\_\_

Residence Tokyo, Japan

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**Inventor's signature** \_\_\_\_\_

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